

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

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| Title of Invention | PREDICTING DEFECT FUTURE EFFECTS IN INTEGRATED CIRCUIT TECHNOLOGY DEVELOPMENT TO FACILITATE SEMICONDUCTOR WAFER LOT DISPOSITION | |
| Application Type: regular, utility | | |
| Attorney Docket Number: H0897 | | |
| Request Not To Publish | | |
| I/We hereby request that the attached application not be published under 37 U.S.C. 122(b). | | |
| I/We hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. | | |
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